Failure Analysis Student – Amazon

DESCRIPTION

· Preparation and inspection of metallographic cross-sections of solder joints and electronic components for routine monitoring and failure analysis.

· Preparation of samples for failure analysis of IC’s

· Take part in the development of techniques for sample preparation

· You will have an opportunity to be exposed to state-of-the-art techniques and tools for debug and failure analysis, like FIB, Electron microscopy and photonic methods for debug and fault isolation.

BASIC QUALIFICATIONS

· Student for B.Sc in Materials/chemical engineering or higher. Or a student for M.Sc in Chemistry. At least one year of remaining studies.

· Available at least 20 hours a week. Working in shifts is also possible.

· Personal skills:

- Organized
- Highly motivated and Diligent
- Hands-on person
- Good teamwork and good communication skills, but yet have the ability to handle tasks independently

Proficiency in written and spoken English

PREFERRED QUALIFICATIONS

· Experience in preparing and inspecting metallographic cross-sections

· Experience with SEM and/or TEM

· Experience with FIB

· Hands-on experience with acids

· Relevant courses in VLSI processing, electronics packaging and assembly, metallurgy, electron microscopy.

https://www.amazon.jobs/en/jobs/758582/failure-analysis-student